



# MODELING CONTACT LINE DYNAMICS IN EVAPORATING MENISCI

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Electronic cooling

Space & Aviation

Evaporative Self  
Assembly



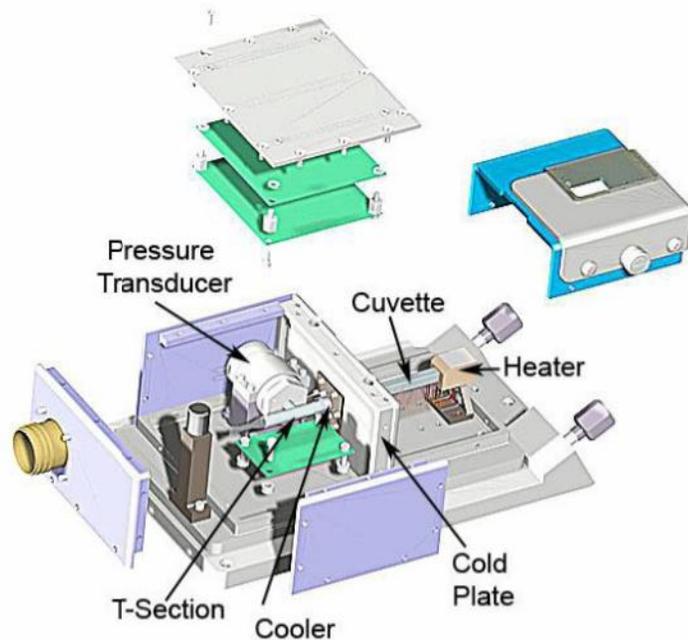
**Rensselaer**  
Polytechnic Institute

COMSOL User's Conference, Boston

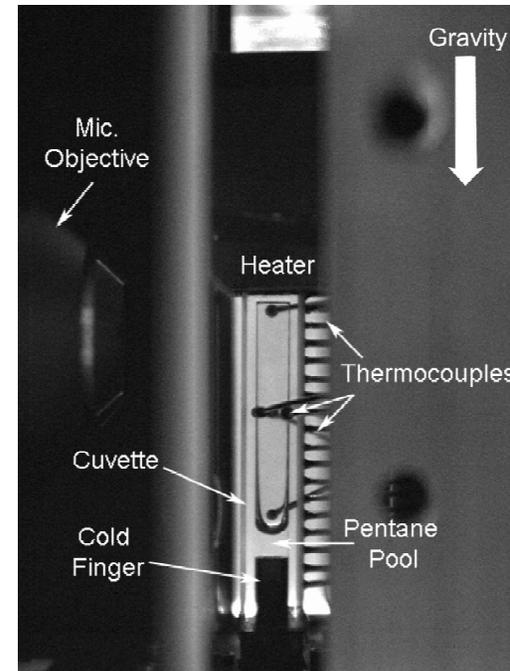


# Experimental System – CVB Experiment

ISS CVB Module



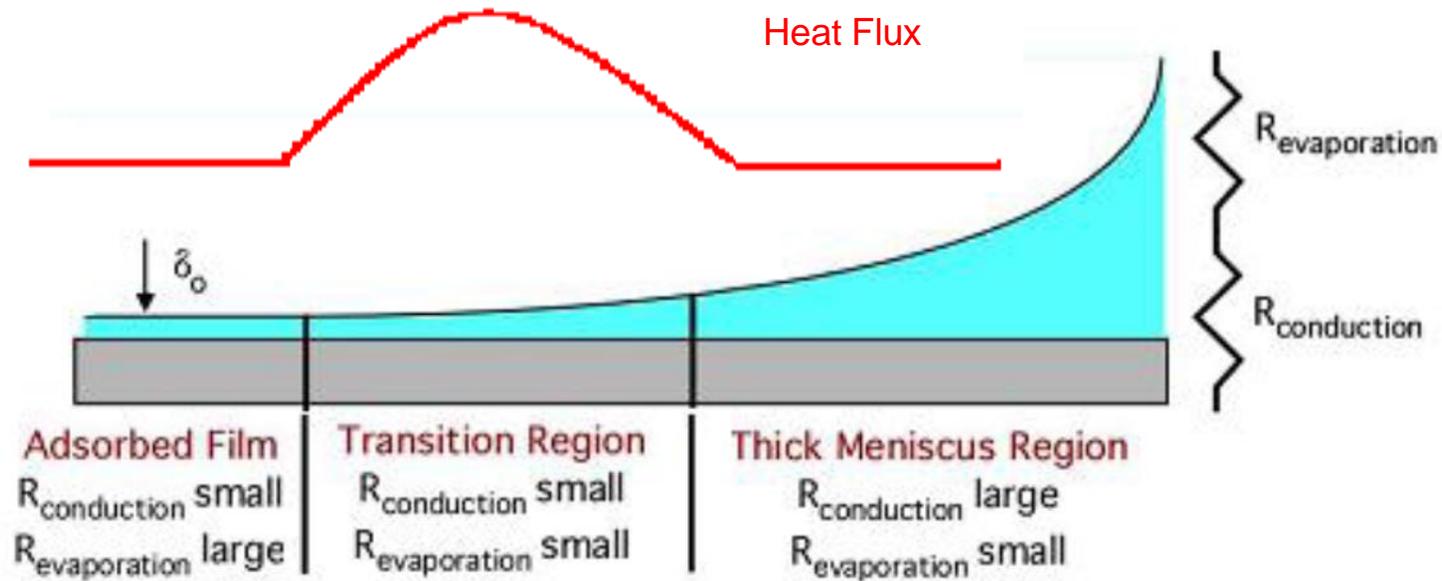
Photograph of Module



- Partially filled cell forms a Constrained Vapor Bubble (CVB) design.
- Wickless heat pipe with transparent walls.
- Goal is to measure the vapor and liquid distributions as the pipe is driven.



# Evaporation from a Thin Film

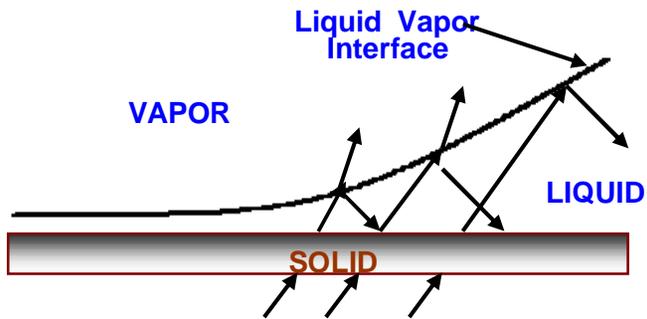


Transition region controls evaporation. Lowest overall resistance.

– Accurate modeling will enable us to engineer optimal surfaces

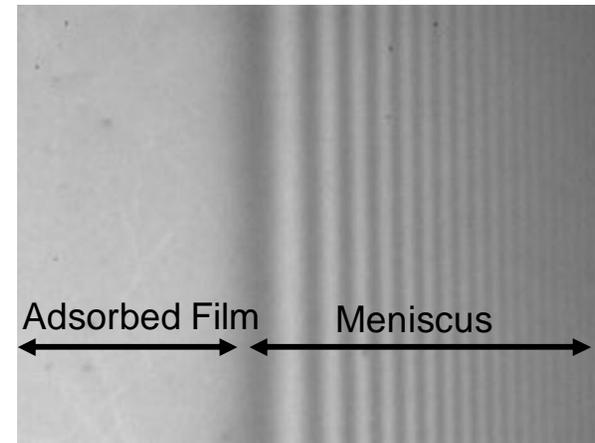


# Reflectivity/Interferometry Technique

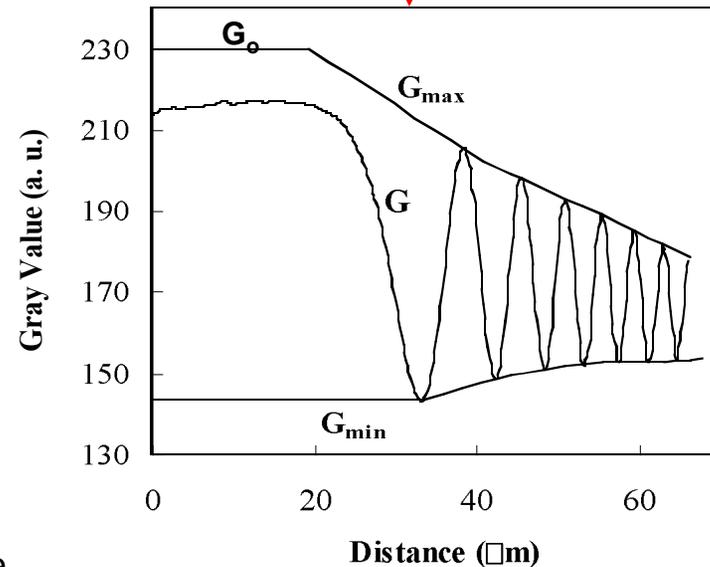


Varying thickness of the meniscus produces an interference pattern

Analysis yields:  
Film thickness profile  
Contact angle  
Interface curvature

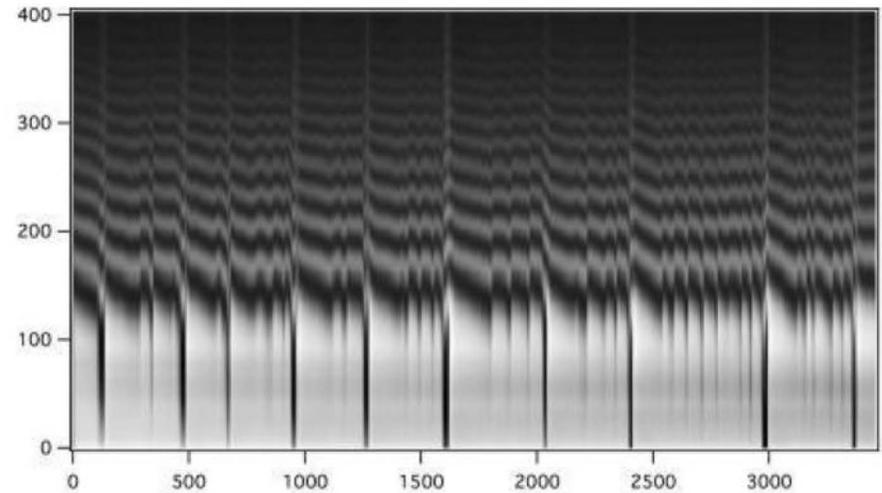
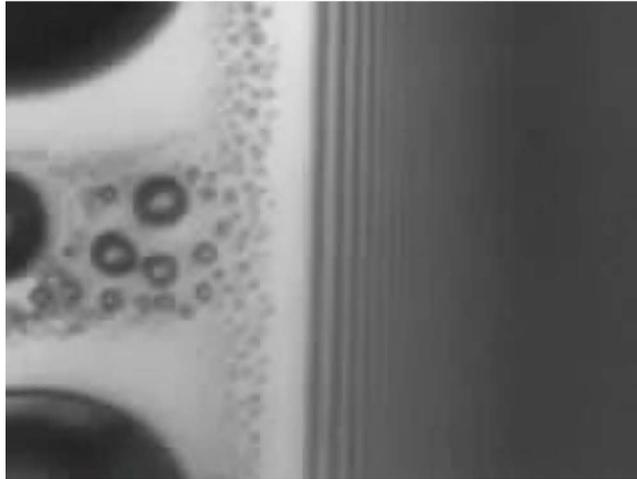


Interference pattern analyzed to obtain gray value at each pixel





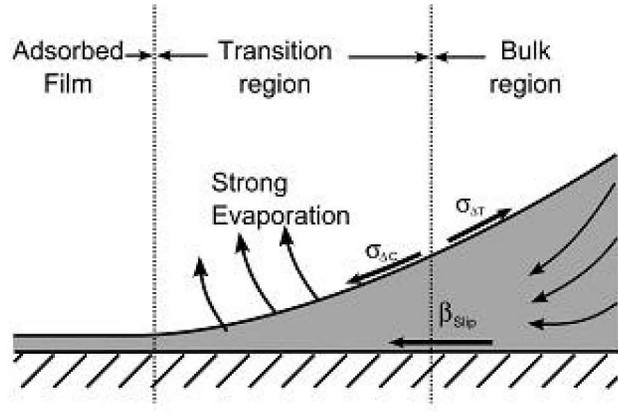
# Evaporating Meniscus – HFE-7000



<b>Fluid</b>	<b>Density (kg/m<sup>3</sup>)</b>	<b>Viscosity (Ns/m<sup>2</sup>)</b>	<b>Surface Tension (N/m)</b>	<b>Heat of Vaporization (J/kg)</b>
HFE-7100	1400	$5.80 \times 10^{-4}$	0.0136	113034



# Fluid Flow Model



- Lubrication approximation used to model fluid flow.
- Navier slip (solid-liquid interface) and Marangoni shear (liquid-vapor interface) boundary conditions applied

$$\mu \frac{d^2 u}{dy^2} = \frac{dP_1}{dx} \quad y=0, \quad u_s = \mu \frac{du}{dy} \Big|_{y=0}$$

$$P_1(x) = P_v \left[ \mu(x)K(x) + \mu(x) \right] \quad y = \mu(x), \quad \mu_{yx} = \frac{d\mu_{lv}}{dx}$$

- Temperature dependence of fluid properties accounts for the capillary, Marangoni and van der Waals forces.
- Mass balance, provides the evaporating mass flux at each pixel location.

$$\mu = \int_0^{\mu} \mu u dy \quad \frac{d\mu}{dx} = \mu \dot{m}_{evp} \quad q'' = \mu h_{fg} \frac{d\mu}{dx}$$



# Heat Transfer at the Contact Line

- Heat transfer at the contact line was modeled using a Kelvin-Clapeyron approach.

$$\frac{d\delta}{dx} = \delta \dot{m}_{evp}$$

$$\dot{m}_{evp} = C \left( \frac{M}{2\delta RT} \right)^{1/2} \left\{ \frac{P_v M h_{fg}}{RT_v T_i} (T_i - T_v) + \frac{V_l P_v}{RT_i} \underbrace{(P_l - P_v)}_{\text{Interface Shape}} \right\}$$

- The temperature difference across the liquid was tied to the mass flux to describe the driving force as a superheat.

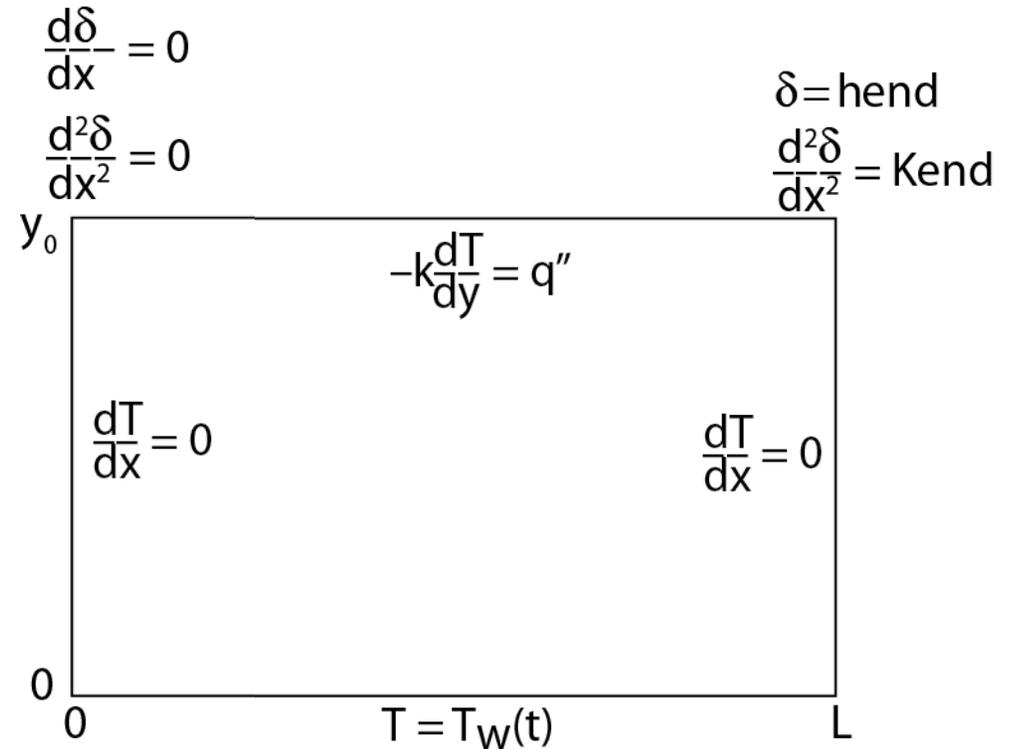
$$T_i(x) - T_w = \delta \left( \frac{\dot{m}_{evp} h_{fg}}{k_l} \right)$$

- Final equation can be written as a 4th order differential equation for the film thickness.



# Comsol Set-Up

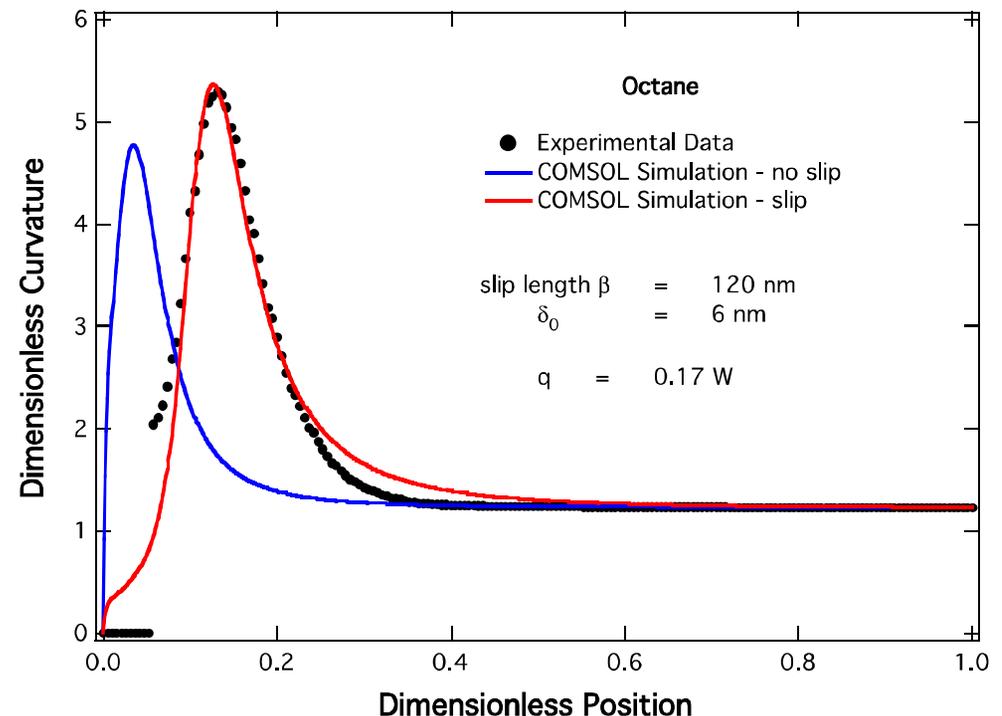
- Split the 4<sup>th</sup> order equation into two 2<sup>nd</sup> order equations for film thickness and interface curvature.
- 1-D weak form on the boundary.
- 2-D conduction heat transfer in the solid.
- Boundary conditions set film thickness and curvature at the thick end, and the curvature and slope at the start (perfectly wetting fluid).





## Simulation Results – Steady-State

- COMSOL simulation was able to reproduce the experimental data from an octane meniscus.
- The incorporation of hydrodynamic slip was necessary to match both the position of the curvature peak and the spread of the peak.
- Peak height is controlled by the thickness of the adsorbed film ahead of the contact line.

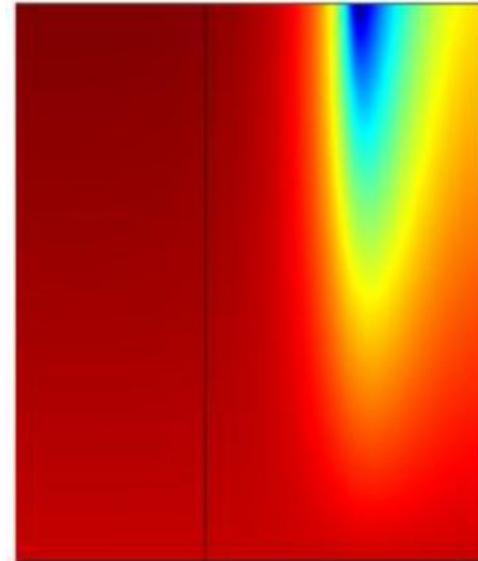




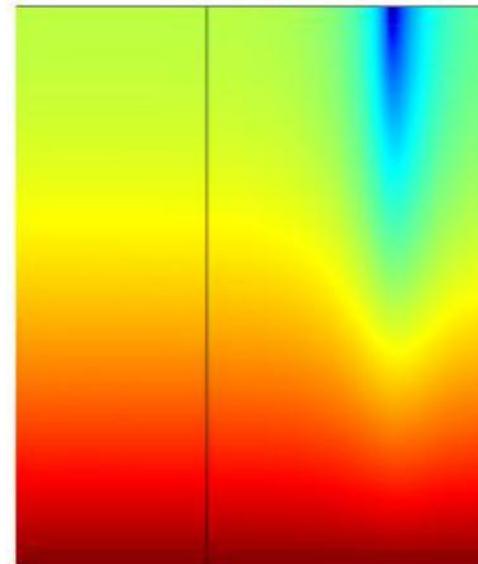
## Simulation Results – Oscillation

- COMSOL simulation was applied to an pentane meniscus.
- Oscillation was established by varying the temperature on the underside of the substrate.
- Plots show snapshots of the temperature profile in the substrate for two different substrate materials at the same time during the oscillation.
- Higher thermal diffusivity leads to a different dynamic mismatch between heat delivered to the film and heat removed via evaporation.

**SiO<sub>2</sub>**



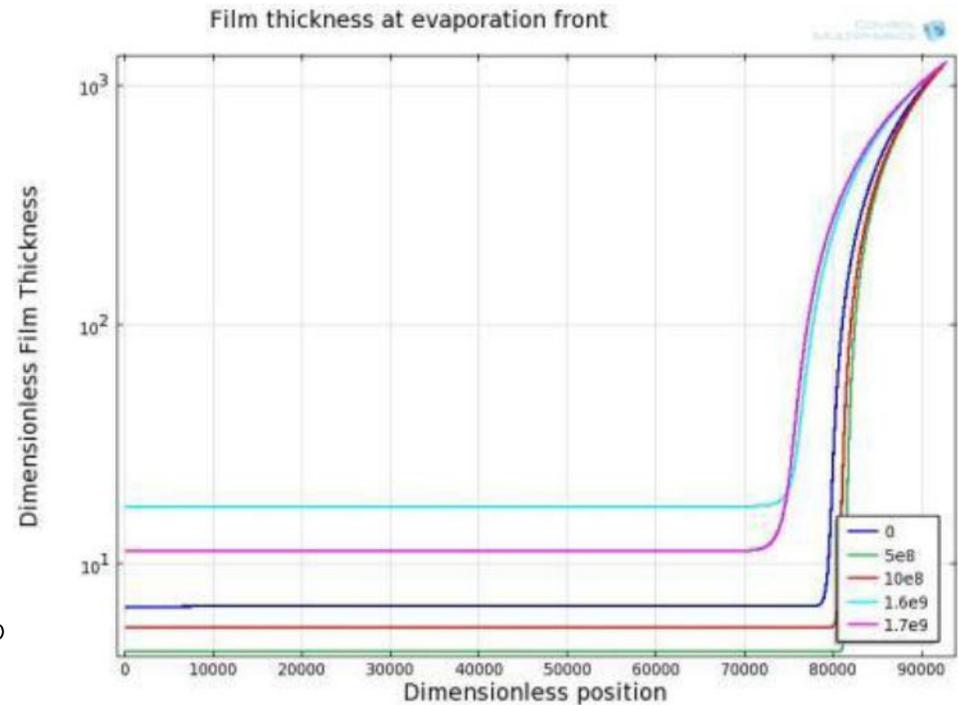
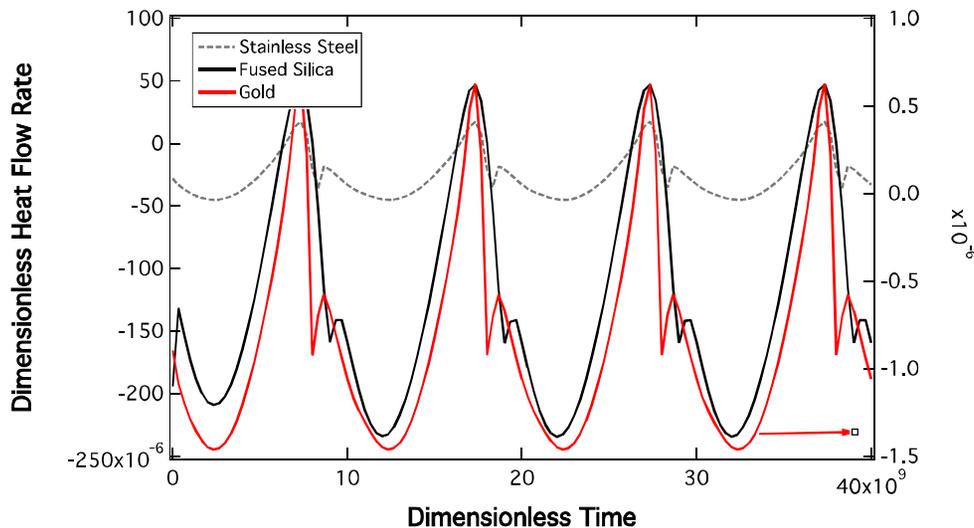
**Au**





# Simulation Results – Oscillation

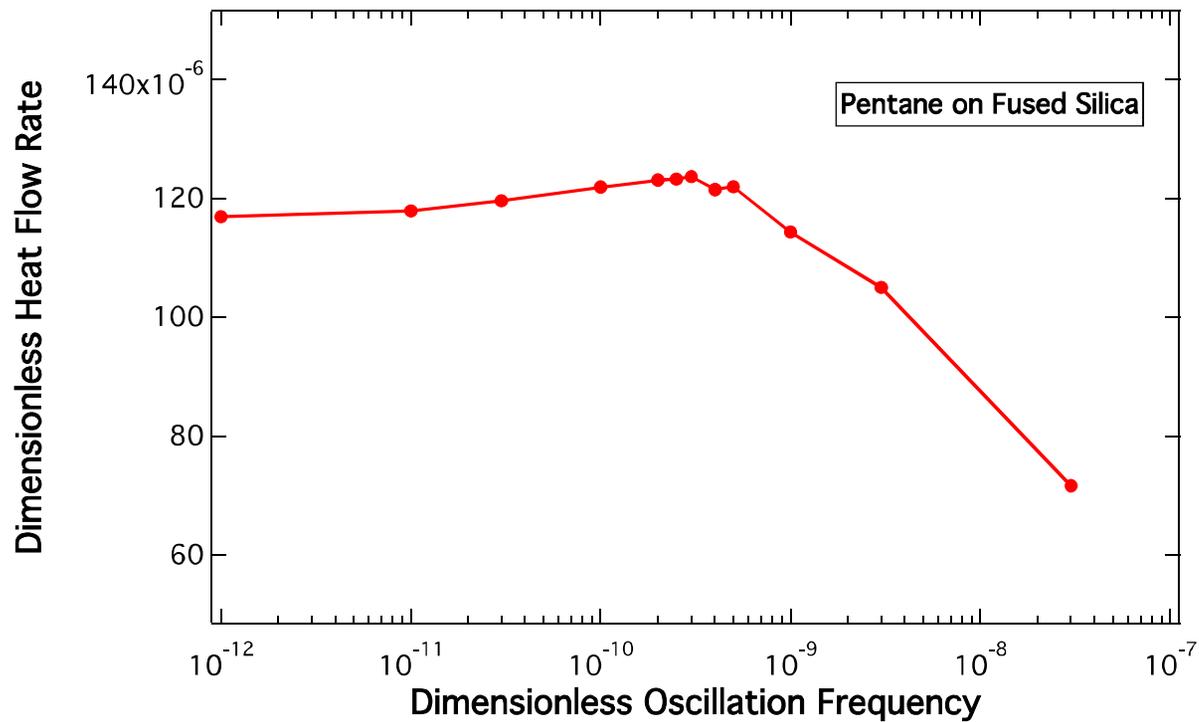
- Achieve large changes in film thickness for small differences in applied temperature (here  $\sim 0.01$  °C)



- Dimensionless heat flow rate changes dramatically with substrate material. The oscillation phase also changes and for certain forcings, the film oscillates at higher frequency.



## Simulation Results – Oscillation



- Film acting as a low-pass filter.
- There is a small resonance that we need to explore further.



## Conclusions

- **We can reproduce some of what we observe in an oscillating evaporating meniscus.**
- **Oscillation amplitude and frequency are related to a mismatch between the heat dissipation rate in the film and the rate at which heat can be delivered from the substrate.**
- **Much more modeling work is needed to match up with actual experimental data and to mimic all the behaviors we observe in the thin film.**